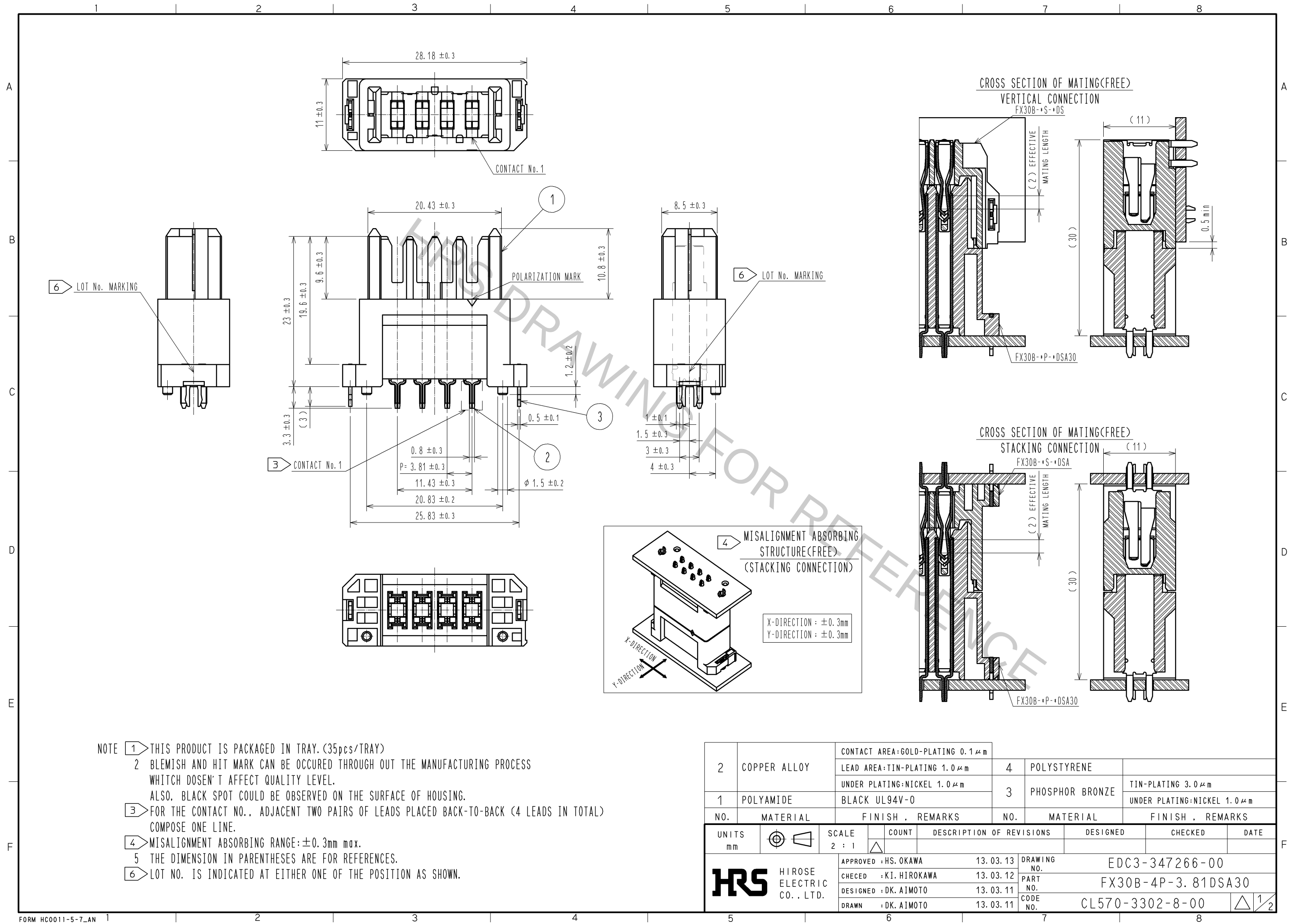
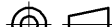
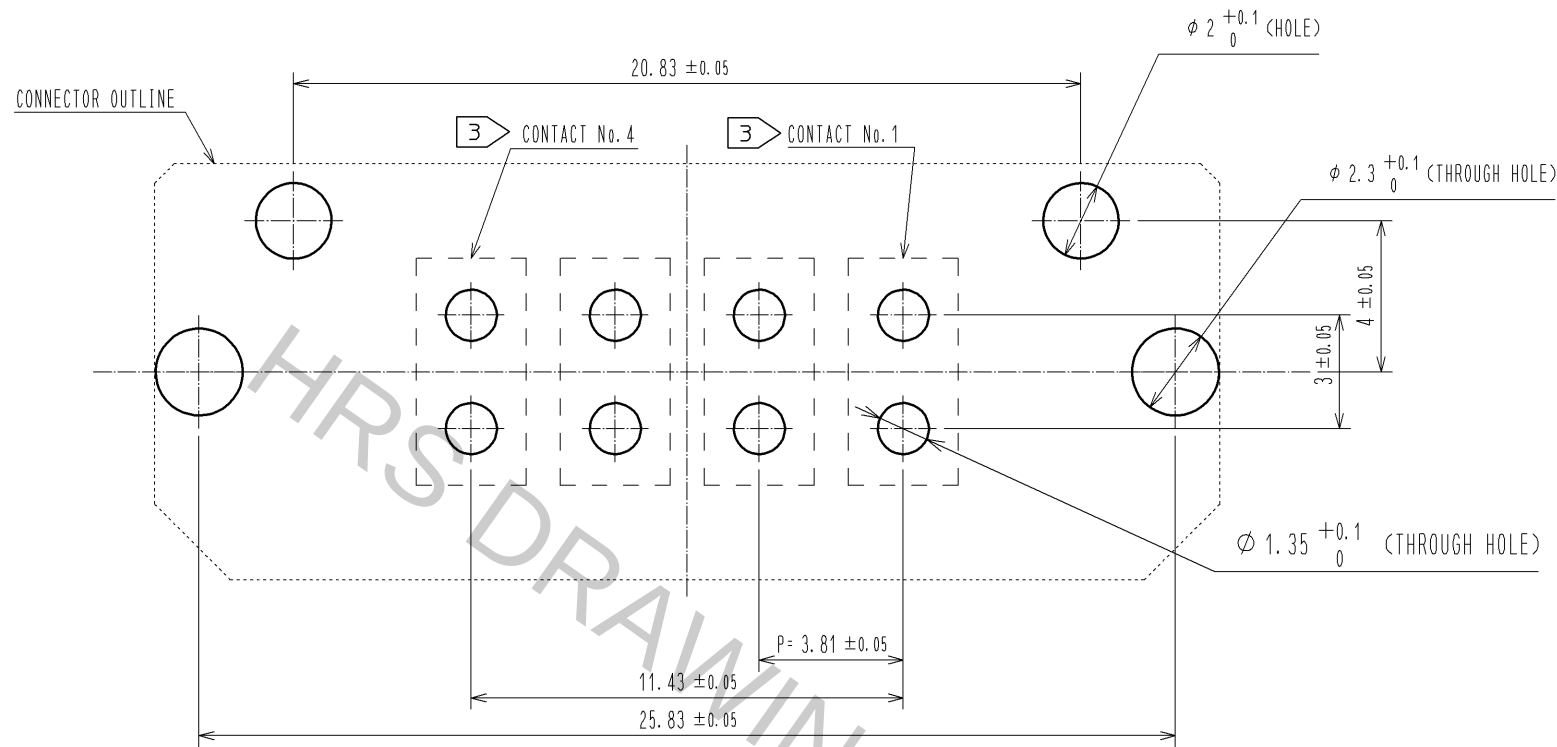




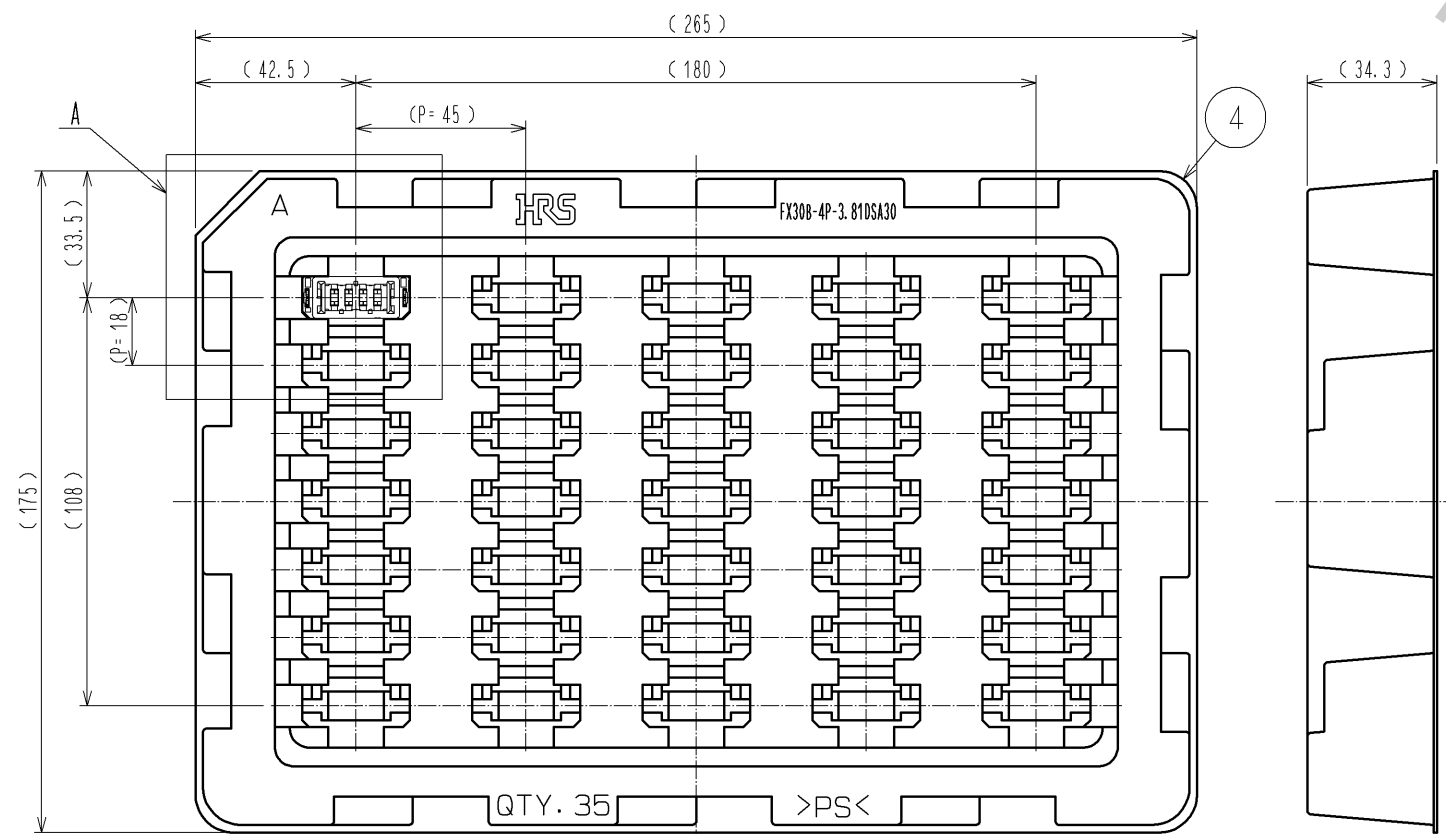
NOTE 1 THIS PRODUCT IS PACKAGED IN TRAY. (35pcs/TRAY)
2 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHITCH DOSEN' T AFFECT QUALITY LEVEL.
ALSO, BLACK SPOT COULD BE OBSERVED ON THE SURFACE OF HOUSING.
3 FOR THE CONTACT NO., ADJACENT TWO PAIRS OF LEADS PLACED BACK-TO-BACK (4 LEADS IN TOTAL) COMPOSE ONE LINE.
4 MISALIGNMENT ABSORBING RANGE: $\pm 0.3\text{mm}$ max.
5 THE DIMENSION IN PARENTHESES ARE FOR REFERENCES.
6 LOT NO. IS INDICATED AT EITHER ONE OF THE POSITION AS SHOWN.

2	COPPER ALLOY	CONTACT AREA:GOLD-PLATING 0.1 μm			4	POLYSTYRENE					
		LEAD AREA:TIN-PLATING 1.0 μm									
		UNDER PLATING:NICKEL 1.0 μm									
1	POLYAMIDE	BLACK UL94V-0			3	PHOSPHOR BRONZE	TIN-PLATING 3.0 μm				
							UNDER PLATING:NICKEL 1.0 μm				
NO.	MATERIAL	FINISH , REMARKS			NO.	MATERIAL	FINISH , REMARKS				
UNITS mm				SCALE 2 : 1		COUNT	DESCRIPTION OF REVISIONS		DESIGNED	CHECKED	DATE
 HIROSE ELECTRIC CO., LTD.		APPROVED : HS. OKAWA			13. 03. 13		DRAWING NO. EDC3-347266-00				
		CHECED : KI. HIROKAWA			13. 03. 12		PART NO. FX30B-4P-3. 81DSA30				
		DESIGNED : DK. AIMOTO			13. 03. 11		CODE NO. CL570-3302-8-00				
		DRAWN : DK. AIMOTO			13. 03. 11						
							 1/2				

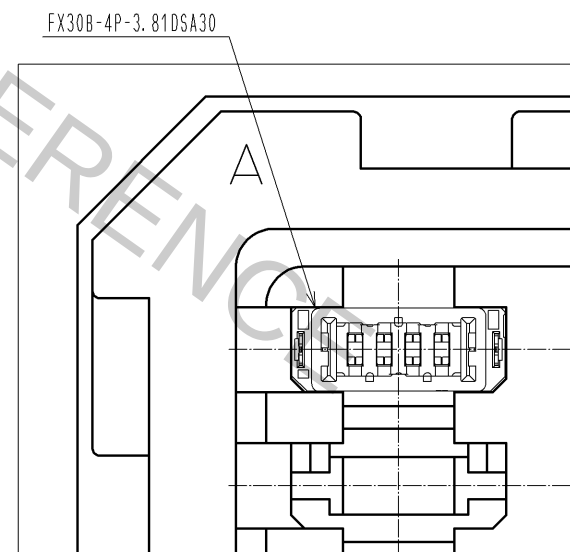
RECOMMENDED HOLE PATTERN DIMENSION OF PCB(5:1)
(CONNECTOR MOUNTING SIDE, PCB THICKNESS: $t=1.6\text{mm}$)



1 DRAWING FOR PACKAGING(1:2)



A(1:1)



HRS

DRAWING NO.	EDC3-347266-00
PART NO.	FX30B-4P-3.81DSA30
CODE NO.	CL570-3302-8-00

2/2